L Number	Hits	Search Text	DB	Time stamp
1	9539	die near5 (attach or attaching or	USPAT;	2003/04/30 11:08
		attachment)	US-PGPUB;	
			EPO; JPO;	·
			DERWENT;	
			IBM_TDB	
2	10693	cyanoacrylate or cyano near2 acrylate	USPAT;	2003/04/30 11:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		/32	IBM_TDB USPAT;	2003/04/30 11:59
3	65	(die near5 (attach or attaching or attachment)) and (cyanoacrylate or cyano	US-PGPUB;	2003/04/30 11:33
		near2 acrylate)	EPO; JPO;	
		Hearz acryrace;	DERWENT;	
			IBM TDB	
4	28539	anaerobic	USPAT;	2003/04/30 11:59
4	2000	· ·	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	1226446	lead or leads	USPĀT;	2003/04/30 11:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	3722	leadframe	USPAT;	2003/04/30 12:03
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	İ
		1 15	IBM_TDB	2003/04/30 12:03
7	1227249	(lead or leads) or leadframe	USPAT;	2003/04/30 12:03
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	707	anaerobic same ((lead or leads) or	USPAT;	2003/04/30 12:03
	'0'	leadframe)	US-PGPUB;	
		ToddIIdino	EPO; JPO;	
			DERWENT;	
		× *	IBM TDB	
9	. 850838	adhesive or glue	USPAT;	2003/04/30 12:03
		•	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	48	(anaerobic same ((lead or leads) or	USPAT;	2003/04/30 12:03
		leadframe)) same (adhesive or glue)	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
11	E20060	chin	IBM_TDB USPAT;	2003/04/30 12:03
11	528069	chip	US-PGPUB;	2003/04/30 12:03
1			EPO; JPO;	
			DERWENT;	
		· ·	IBM TDB	
12	406546	die	USPAT;	2003/04/30 12:04
	100010		US-PGPUB;	
	İ		EPO; JPO;	
	{		DERWENT;	
	j		IBM_TDB	
13	891770	chip or die	USPAT;	2003/04/30 12:04
			US-PGPUB;	
			EPO; JPO;	
	ļ		DERWENT;	
1			IBM_TDB	0000/01/00 15 5
14	11		USPAT;	2003/04/30 12:05
		leadframe)) same (adhesive or glue)) and	US-PGPUB;	,
		(chip or die)	EPO; JPO;	
			DERWENT;	
L			IBM_TDB	

L Number	Hits	Search Text	DB	Time stamp
1	3722	leadframe	USPAT;	2003/04/30 09:54
_			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	2002/04/20 00.55
2	535077	chip or semiconductor near5 die	USPAT; US-PGPUB;	2003/04/30 09:55
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	2062	leadframe same (chip or semiconductor	USPĀT;	2003/04/30 09:55
		near5 die)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	0.001		IBM_TDB	2002/04/20 00.55
4	9601	cyanoacrylate	USPAT;	2003/04/30 09:55
			US-PGPUB; EPO; JPO;	
1			DERWENT;	
			IBM TDB	
5	13	(leadframe same (chip or semiconductor	USPAT;	2003/04/30 10:07
-		near5 die)) and cyanoacrylate	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		<u> </u>	IBM_TDB	0000/04/00 10 01
6	62956	frame) near5(lead or leads	USPAT;	2003/04/30 10:21
1			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	19589	(chip or semiconductor near5 die) same	USPAT;	2003/04/30 10:08
'	13003	(frame) near5(lead or leads)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	·
_			IBM_TDB	
8	27	1 -4	USPAT;	2003/04/30 10:19
		near5 die) same (frame) near5(lead or leads))	US-PGPUB; EPO; JPO;	
1		[ TeadS) )	DERWENT;	
-			IBM TDB	
9	1	leadframe	USOCR	2003/04/30 10:19
10	24900	chip	USOCR	2003/04/30 10:19
11	210	cyanoacrylate	USOCR	2003/04/30 10:19
12	7	chip and cyanoacrylate	USOCR	2003/04/30 10:20
13	18811		USOCR	2003/04/30 10:20
14	62056	semiconductor and cyanoacrylate frame) near5(lead or leads	USOCR USPAT;	2003/04/30 10:20 2003/04/30 10:22
15	62956		US-PGPUB;	2003/04/30 10:22
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	3354585		USPĀT;	2003/04/30 10:22
		attachment or attach or bond or bonds or	US-PGPUB;	-
		bonding	EPO; JPO;	
			DERWENT;	
17	60056	from poor (load or loads)	IBM_TDB	2003/04/30 10.22
17	62956	frame near5(lead or leads)	USPAT; US-PGPUB;	2003/04/30 10:23
			EPO; JPO;	v
			DERWENT;	
			IBM TDB	
18	1594	(leadframe same (chip or semiconductor	USPĀT;	2003/04/30 10:23
		near5 die)) same (bonded or attached or	US-PGPUB;	
		attaching or attachment or attach or bond	EPO; JPO;	
		or bonds or bonding)	DERWENT;	
1.0	050000		IBM_TDB	2002/04/20 10 00
19	850838	adhesive or glue	USPAT;	2003/04/30 10:23
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
	<u> </u>	<u> </u>		L

		1 / / 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	TICDAM.	2003/04/30 10:23
20	411		USPAT;	2003/04/30 10:23
		near5 die)) same (bonded or attached or	US-PGPUB;	
		attaching or attachment or attach or bond	EPO; JPO;	
		or bonds or bonding)) same (adhesive or	DERWENT;	
	1.46	glue)	IBM_TDB   USPAT;	2003/04/30 10:24
21	146	superglue		2003/04/30 10:24
	1	_	US-PGPUB;	<u> </u>
		·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/04/20 10:24
22	0	, , , =	USPAT;	2003/04/30 10:24
		near5 die)) same (bonded or attached or	US-PGPUB;	
		attaching or attachment or attach or bond	EPO; JPO;	
		or bonds or bonding)) same (adhesive or	DERWENT;	
		glue)) and superglue	IBM_TDB	2002/04/20 10:24
23	204456	acrylate	USPAT;	2003/04/30 10:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
24	211033	cyanoacrylate or acrylate	USPAT;	2003/04/30 10:24
	1		US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
	_		IBM_TDB	0000/04/00 10 00
25	64	superglue and (cyanoacrylate or acrylate)	USPAT;	2003/04/30 10:26
	Ì		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/04/00 10 00
26	10	1 ' '	USPAT;	2003/04/30 10:28
		near5 die)) same (bonded or attached or	US-PGPUB;	
	1	attaching or attachment or attach or bond	EPO; JPO;	
		or bonds or bonding)) same (adhesive or	DERWENT;	
		glue)) and (cyanoacrylate or acrylate)	IBM_TDB	0000/04/00 10 00
27	7805	radiopaque	USPAT;	2003/04/30 10:29
	İ		US-PGPUB;	·
			EPO; JPO;	
			DERWENT;	
		11	IBM_TDB USPAT;	2003/04/30 10:29
28	0			2003/04/30 10:29
		semiconductor near5 die)) same (bonded or	US-PGPUB;	
		attached or attaching or attachment or attach or bond or bonds or bonding)) same	EPO; JPO; DERWENT;	
			IBM TDB	
20	_	(adhesive or glue)) radiopaque and (leadframe same (chip or	USPAT;	2003/04/30 10:29
29	0	radiopaque and (leadiname same (chip of semiconductor near5 die))	US-PGPUB;	2003/04/30 10.29
		Semiconductor hears die//	EPO; JPO;	
			DERWENT;	
			IBM TDB	
30	606	radiopaque and cyanoacrylate	USPAT;	2003/04/30 10:30
30	000	radiopaque and cyanoacryrate	US-PGPUB;	2003/04/30 10.30
			EPO; JPO;	
			DERWENT;	
		·	IBM TDB	
31	0	   (radiopaque and cyanoacrylate) and	USPAT;	2003/04/30 10:30
1 31	1	leadframe	US-PGPUB;	2000,04,00 10.00
		TOUGETAME	EPO; JPO;	
			DERWENT;	,
			IBM TDB	
32	0	(radiopaque and cyanoacrylate) and (frame	USPAT;	2003/04/30 10:30
""		near5(lead or leads))	US-PGPUB;	2000,03,00 10.00
		Incaro(Tead Of Teads))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
		<u> </u>	1100	L

		<u> </u>		
15	451		USPAT;	2003/04/30 08:24
		semiconductor) and (adhesive same	US-PGPUB;	
		acrylate)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	1	adhasive same cyanoacrylate	USPAT;	2003/04/30 08:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
17	5418	adhesive same cyanoacrylate	USPAT;	2003/04/30 08:25
1 - '	0120		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	*
18	528069	chip .	USPAT;	2003/04/30 08:25
1.0	320003	Chip	US-PGPUB;	2003/01/30 00.20
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
1,0	51	   (adhesive same cyanoacrylate) same chip	USPAT;	2003/04/30 08:26
19	31.	(adhesive same cyanoaciyiate) same chip	US-PGPUB;	2003/04/30 08.20
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
20	5830	fast near7 (cure or curing or cured or	USPAT;	2003/04/30 08:27
20	3030	cures)	US-PGPUB;	2003/04/30 08.27
		cures)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
1 21	2212	midk nearly (auna or auring or gured or	USPAT;	2003/04/30 08:27
21	2212	quick near7 (cure or curing or cured or cures)	US-PGPUB;	2003/04/30 08:27
		Curesi	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	7040	/6 /	USPAT;	2003/04/30 08:27
22	7842			2003/04/30 08:2/
		cures)) or (quick near7 (cure or curing or	US-PGPUB;	
1	1 '	cured or cures))	EPO; JPO; DERWENT;	
		//6	IBM_TDB	2003/04/20 00:07
23	2		USPAT;	2003/04/30 08:27
		cures)) or (quick near7 (cure or curing or	US-PGPUB;	
		cured or cures))) and ((adhesive same	EPO; JPO;	
		cyanoacrylate) same chip )	DERWENT;	
1	1	I	IBM TDB	

T.	Number	Hits	Search Text	DB	Time stamp
1	Number	9601		USPAT;	2003/04/30 08:17
-				US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
				IBM_TDB	
2	0	1227249	lead or leads or leadframe	USPAT;	2003/04/30 08:17
	i			US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
	İ	2719		IBM_TDB USPAT;	2003/04/30 08:18
3		2/19	cyanoacrylate and (lead or leads or leadframe)	US-PGPUB;	2003/04/30 08.10
			leadilame)	EPO; JPO;	
1			·	DERWENT;	
				IBM TDB	
4		286	cyanoacrylate same (lead or leads or	USPAT;	2003/04/30 08:18
1			leadframe)	US-PGPUB;	
				EPO; JPO;	
1				DERWENT;	
				IBM_TDB	
5		1226446	lead or leads	USPAT;	2003/04/30 08:18
			4	US-PGPUB;	
1				EPO; JPO;	
				DERWENT;	
1		205		IBM TDB	2002/04/20 00.10
6	ļ	285	cyanoacrylate same (lead or leads)	USPAT; US-PGPUB;	2003/04/30 08:19
				EPO; JPO;	
				DERWENT;	
				IBM TDB	
7		1220310	semiconductor	USPAT;	2003/04/30 08:19
′		1220310		US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
				IBM TDB	
8		26	(cyanoacrylate same (lead or leads)) and	USPĀT;	2003/04/30 08:19
			semiconductor	US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
_				IBM_TDB	2002/04/20 00:10
9		3722	leadframe	USPAT;	2003/04/30 08:19
				US-PGPUB; EPO; JPO;	
	•		•	DERWENT;	
i				IBM TDB	
10		5	leadframe and ((cyanoacrylate same (lead	USPAT;	2003/04/30 08:23
- "		5	or leads)) and semiconductor)	US-PGPUB;	
				EPO; JPO;	
	İ			DERWENT;	
				IBM_TDB	
11		204456	acrylate	USPĀT;	2003/04/30 08:23
				US-PGPUB;	, ,
1				EPO; JPO;	
	,			DERWENT;	
		22222		IBM_TDB	2002/04/20 00 00
12		39108	(lead or leads) and acrylate	USPĀT;	2003/04/30 08:23
!				US-PGPUB; EPO; JPO;	
				DERWENT;	
				IBM TDB	
13		3408	((lead or leads) and acrylate) and	USPAT;	2003/04/30 08:24
``		3400	((lead of leads) and acrylate, and   semiconductor	US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
				IBM TDB	
14		21332	adhesive same acrylate	USPAT;	2003/04/30 08:24
			-	US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
				IBM TDB	